

Title (en)
LEAD-FREE PIEZOELECTRIC CERAMIC COMPOSITION, METHOD FOR PRODUCING SAME, PIEZOELECTRIC ELEMENT USING LEAD-FREE PIEZOELECTRIC CERAMIC COMPOSITION, ULTRASONIC PROCESSING MACHINE, ULTRASONIC DRIVE DEVICE, AND SENSING DEVICE

Title (de)
BLEIFREIE PIEZOELEKTRISCHE KERAMIKZUSAMMENSETZUNG, VERFAHREN ZU IHRER HERSTELLUNG, PIEZOELEKTRISCHES ELEMENT MIT DER BLEIFREIEN PIEZOELEKTRISCHEN KERAMIKZUSAMMENSETZUNG, ULTRASCHALLVERARBEITUNGSMASCHINE, ULTRASCHALLANTRIEBSVORRICHTUNG UND SENSOR

Title (fr)
COMPOSITION DE CÉRAMIQUE PIÉZOÉLECTRIQUE EXEMPTÉ DE PLOMB, SON PROCÉDÉ DE PRODUCTION, ÉLÉMENT PIÉZOÉLECTRIQUE UTILISANT LA COMPOSITION DE CÉRAMIQUE PIÉZOÉLECTRIQUE EXEMPTÉ DE PLOMB, MACHINE DE TRAITEMENT PAR DES ULTRASONS, DISPOSITIF D'ENTRAÎNEMENT À ULTRASONS ET DISPOSITIF CAPTEUR

Publication
EP 2733131 A1 20140521 (EN)

Application
EP 12811521 A 20120704

Priority
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• JP 2012004329 W 20120704

Abstract (en)
A lead-free piezoelectric ceramic composition mainly includes a first crystal phase (KNN phase) and a second crystal phase (NTK phase). In the first crystal phase (KNN phase), a plurality of crystal grains formed of an alkali niobate/tantalate perovskite oxide having piezoelectric characteristics is bound to each other in a deposited state. The second crystal phase (NTK phase) is formed of a compound containing titanium (Ti) and fills spaces between the crystal grains in the first crystal phase.

IPC 8 full level
C04B 35/495 (2006.01); **B06B 1/06** (2006.01); **C04B 35/626** (2006.01); **G01L 23/22** (2006.01); **H10N 30/00** (2023.01); **H10N 30/01** (2023.01); **H10N 30/045** (2023.01); **H10N 30/093** (2023.01); **H10N 30/097** (2023.01); **H10N 30/20** (2023.01); **H10N 30/50** (2023.01); **H10N 30/853** (2023.01)

CPC (source: EP US)
B06B 1/0618 (2013.01 - EP US); **C04B 35/495** (2013.01 - EP US); **C04B 35/62685** (2013.01 - EP US); **C04B 35/64** (2013.01 - US); **G01L 23/222** (2013.01 - EP US); **H10N 30/097** (2023.02 - EP US); **H10N 30/8542** (2023.02 - EP US); **C04B 2235/3201** (2013.01 - EP US); **C04B 2235/3203** (2013.01 - EP US); **C04B 2235/3208** (2013.01 - EP US); **C04B 2235/3213** (2013.01 - EP US); **C04B 2235/3215** (2013.01 - EP US); **C04B 2235/3224** (2013.01 - EP US); **C04B 2235/3234** (2013.01 - EP US); **C04B 2235/3244** (2013.01 - EP US); **C04B 2235/3251** (2013.01 - EP US); **C04B 2235/3267** (2013.01 - EP US); **C04B 2235/3272** (2013.01 - EP US); **C04B 2235/3275** (2013.01 - EP US); **C04B 2235/3279** (2013.01 - EP US); **C04B 2235/3281** (2013.01 - EP US); **C04B 2235/3284** (2013.01 - EP US); **C04B 2235/3291** (2013.01 - EP US); **C04B 2235/3298** (2013.01 - EP US); **C04B 2235/768** (2013.01 - EP US); **C04B 2235/79** (2013.01 - EP US); **C04B 2235/80** (2013.01 - EP US)

Cited by
EP2937322A3; US9871187B2

Designated contracting state (EPC)
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